

# 1.5V Drive Pch MOSFET

## RW1C025ZP

### ● Structure

Silicon P-channel MOSFET

### ● Features

- 1) Low On-resistance.
- 2) Small high power package.
- 3) Low voltage drive.(1.5V)

### ● Application

Switching

### ● Packaging specifications

| Type      | Package | Taping |
|-----------|---------|--------|
|           | Code    | T2CR   |
| RW1C025ZP | 8000    | ○      |

### ● Absolute maximum ratings (Ta = 25°C)

| Parameter                      | Symbol           | Limits          | Unit |     |
|--------------------------------|------------------|-----------------|------|-----|
| Drain-source voltage           | V <sub>DSS</sub> | -20             | V    |     |
| Gate-source voltage            | V <sub>GSS</sub> | ±10             | V    |     |
| Drain current                  | Continuous       | I <sub>D</sub>  | ±2.5 | A   |
|                                | Pulsed           | I <sub>DP</sub> | *1   | ±10 |
| Source current<br>(Body Diode) | Continuous       | I <sub>S</sub>  | -0.5 | A   |
|                                | Pulsed           | I <sub>SP</sub> | *1   | -10 |
| Power dissipation              | P <sub>D</sub>   | *2              | 0.7  | W   |
| Channel temperature            | T <sub>ch</sub>  | 150             | °C   |     |
| Range of storage temperature   | T <sub>stg</sub> | -55 to +150     | °C   |     |

\*1 Pw≤10μs, Duty cycle≤1%

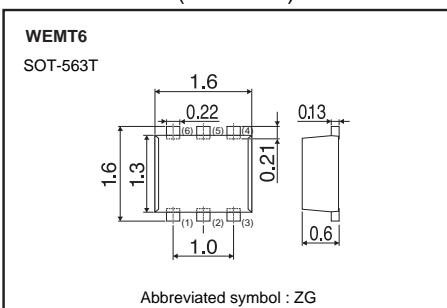
\*2 Mounted on a ceramic board.

### ● Thermal resistance

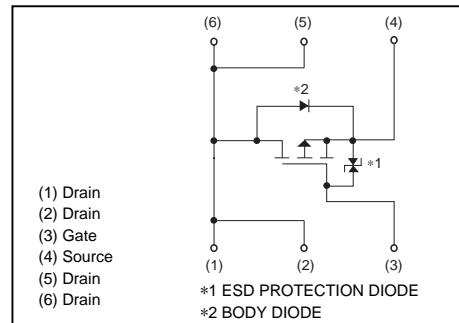
| Parameter          | Symbol                  | Limits | Unit   |
|--------------------|-------------------------|--------|--------|
| Channel to Ambient | R <sub>th</sub> (ch-a)* | 179    | °C / W |

\*Mounted on a ceramic board.

### ● Dimensions (Unit : mm)



### ● Inner circuit



## ● Electrical characteristics (Ta = 25°C)

| Parameter                               | Symbol                | Min. | Typ. | Max. | Unit | Conditions                                    |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage                     | I <sub>GSS</sub>      | -    | -    | ±10  | µA   | V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V    |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub>  | -20  | -    | -    | V    | I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V     |
| Zero gate voltage drain current         | I <sub>DSS</sub>      | -    | -    | -1   | µA   | V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V    |
| Gate threshold voltage                  | V <sub>GS(th)</sub>   | -0.3 | -    | -1.0 | V    | V <sub>DS</sub> =-10V, I <sub>D</sub> =-1mA   |
| Static drain-source on-state resistance | R <sub>DS(on)</sub> * | -    | 48   | 65   | mΩ   | I <sub>D</sub> =-2.5A, V <sub>GS</sub> =-4.5V |
|   |                       | -    | 65   | 90   |      | I <sub>D</sub> =-1.2A, V <sub>GS</sub> =-2.5V |
|   |                       | -    | 90   | 135  |      | I <sub>D</sub> =-1.2A, V <sub>GS</sub> =-1.8V |
|   |                       | -    | 120  | 240  |      | I <sub>D</sub> =-0.5A, V <sub>GS</sub> =-1.5V |
| Forward transfer admittance             | Y <sub>fs</sub>  *    | 2.2  | -    | -    | S    | I <sub>D</sub> =-2.5A, V <sub>DS</sub> =-10V  |
| Input capacitance                       | C <sub>iss</sub>      | -    | 1300 | -    | pF   | V <sub>DS</sub> =-10V                         |
| Output capacitance                      | C <sub>oss</sub>      | -    | 90   | -    | pF   | V <sub>GS</sub> =0V                           |
| Reverse transfer capacitance            | C <sub>rss</sub>      | -    | 70   | -    | pF   | f=1MHz  |
| Turn-on delay time                      | t <sub>d(on)*</sub>   | -    | 9    | -    | ns   | I <sub>D</sub> =-1.2A, V <sub>DD</sub> =-10V  |
| Rise time                               | t <sub>r</sub> *      | -    | 18   | -    | ns   | V <sub>GS</sub> =-4.5V                        |
| Turn-off delay time                     | t <sub>d(off)*</sub>  | -    | 110  | -    | ns   | R <sub>L</sub> =8.3Ω                          |
| Fall time                               | t <sub>f</sub> *      | -    | 50   | -    | ns   | R <sub>G</sub> =10Ω                           |
| Total gate charge                       | Q <sub>g</sub> *      | -    | 21   | -    | nC   | I <sub>D</sub> =-2.5A                         |
| Gate-source charge                      | Q <sub>gs</sub> *     | -    | 4    | -    | nC   | V <sub>DD</sub> =-10V                         |
| Gate-drain charge                       | Q <sub>gd</sub> *     | -    | 3    | -    | nC   | V <sub>GS</sub> =-4.5V                        |

\*Pulsed

## ● Body diode characteristics (Source-Drain) (Ta = 25°C)

| Parameter       | Symbol            | Min. | Typ. | Max. | Unit | Conditions                                 |
|-----------------|-------------------|------|------|------|------|--|
| Forward Voltage | V <sub>SD</sub> * | -    | -    | -1.2 | V    | I <sub>s</sub> =-2.5A, V <sub>GS</sub> =0V |

\*Pulsed

● Electrical characteristic curves ( $T_a=25^\circ\text{C}$ )

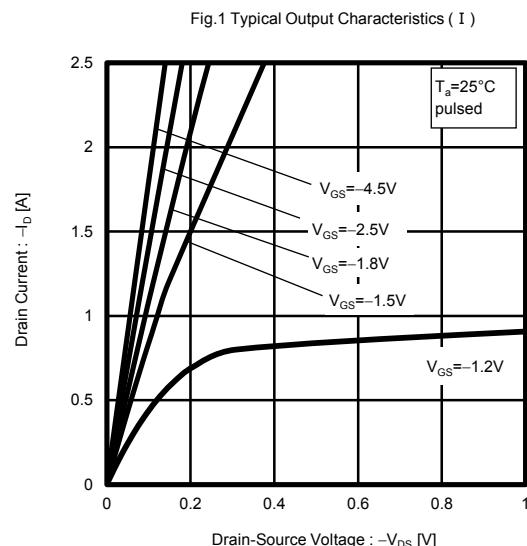


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

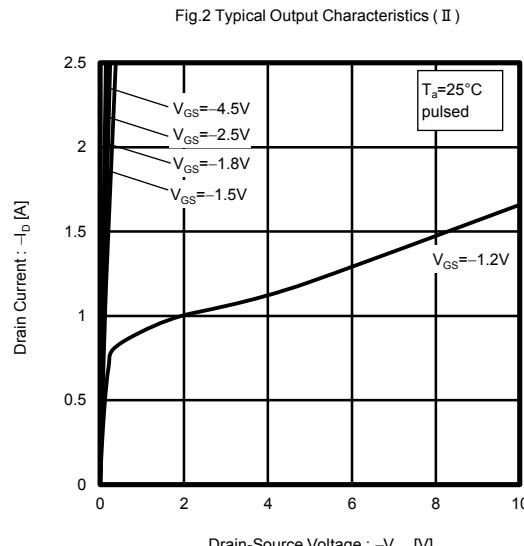


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

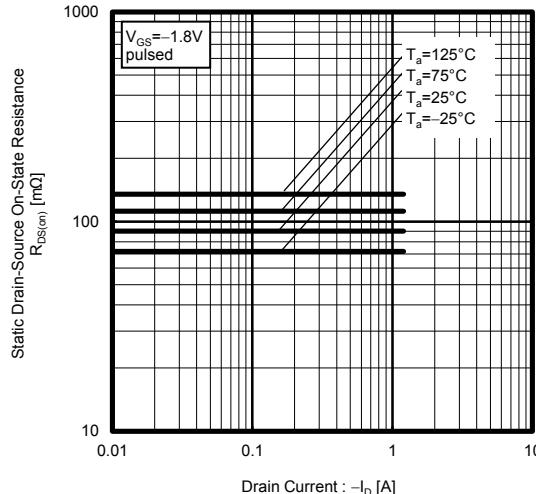
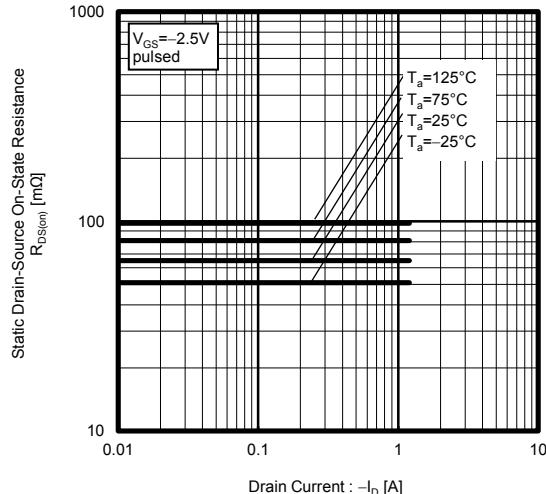
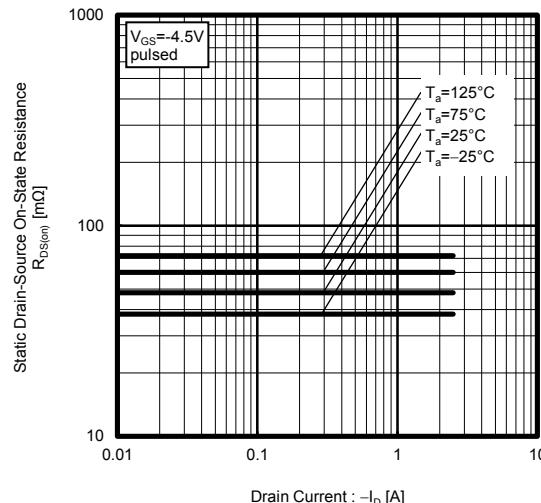
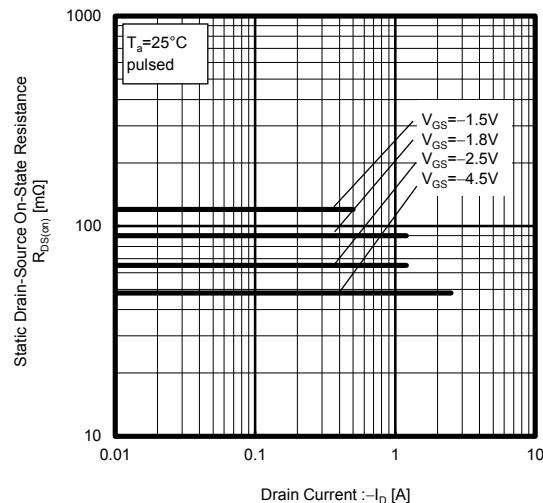


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current

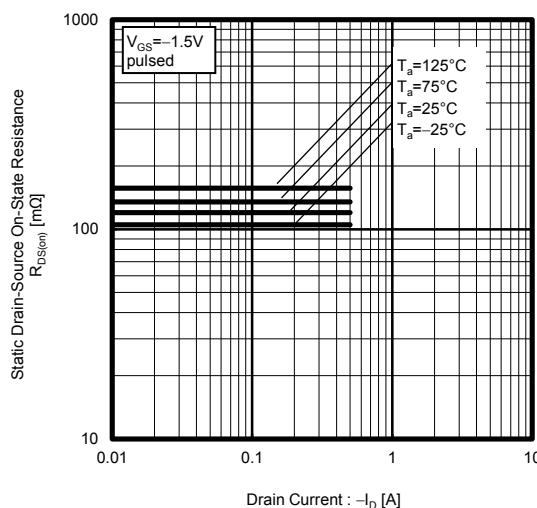


Fig.8 Forward Transfer Admittance vs. Drain Current

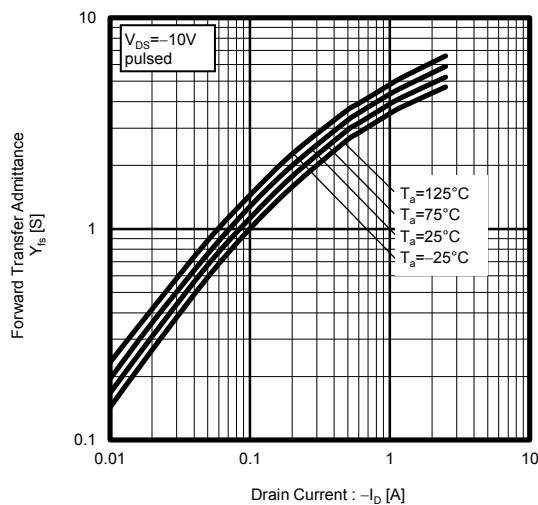


Fig.9 Typical Transfer Characteristics

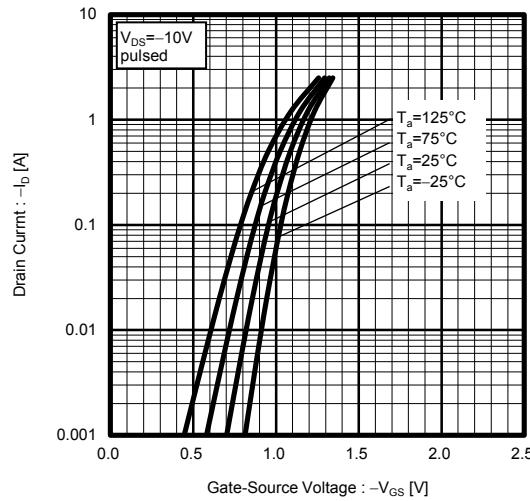


Fig.10 Source Current vs. Source-Drain Voltage

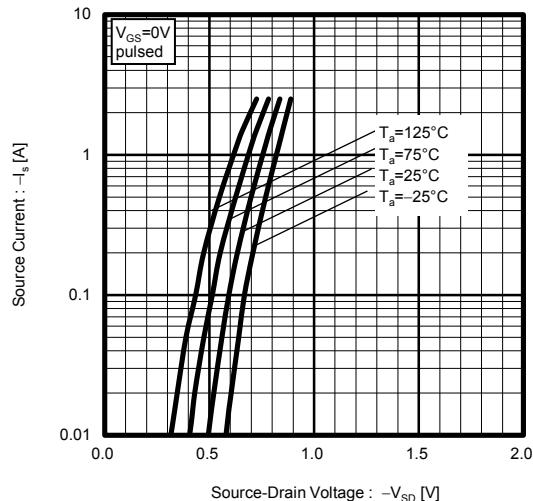


Fig.11 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

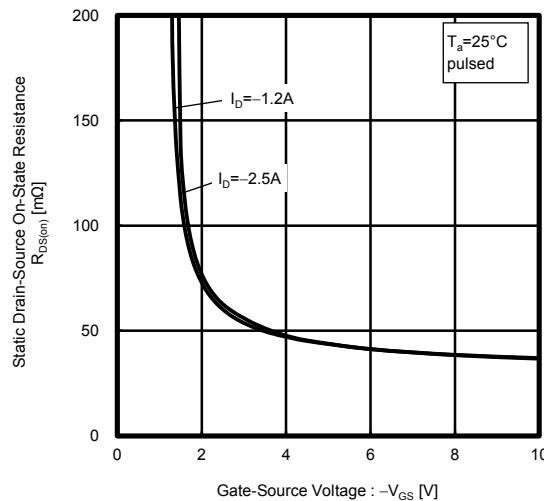


Fig.12 Switching Characteristics

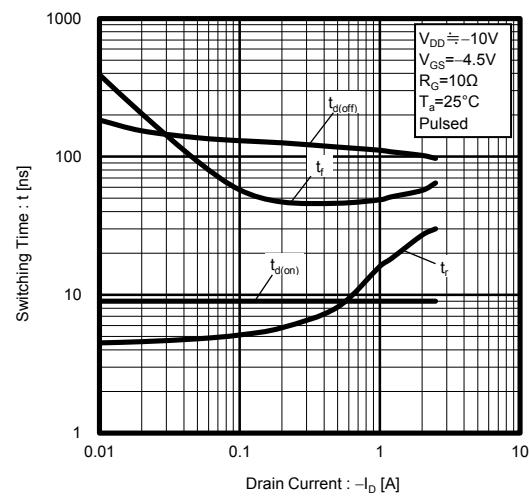


Fig.13 Dynamic Input Characteristics

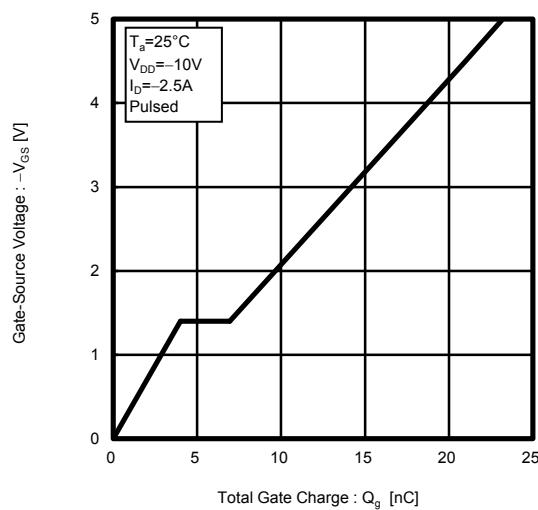
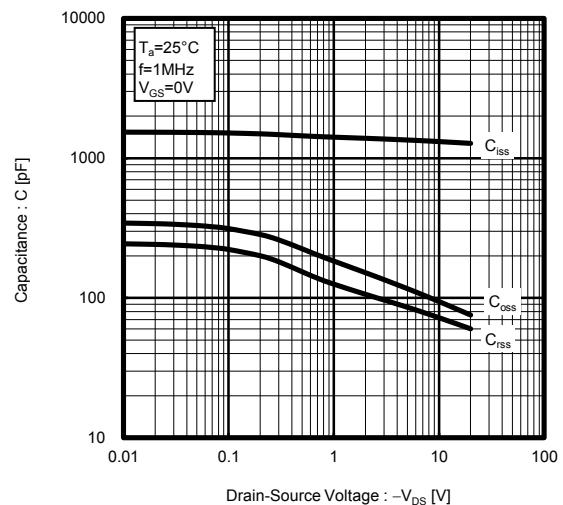


Fig.14 Typical Capacitance vs. Drain-Source Voltage



● Measurement circuits

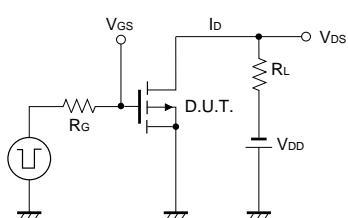


Fig.1-1 Switching Time Measurement Circuit

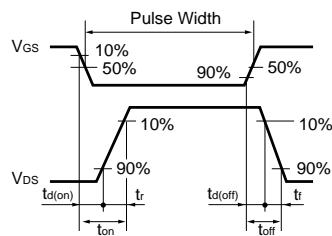


Fig.1-2 Switching Waveforms

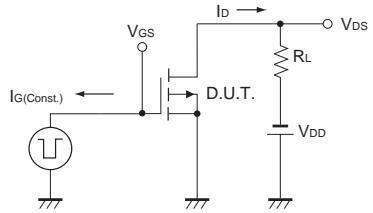


Fig.2-1 Gate Charge Measurement Circuit

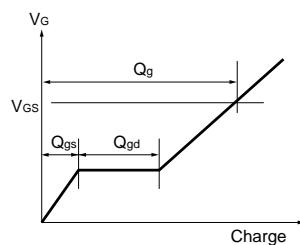


Fig.2-2 Gate Charge Waveform

● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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